

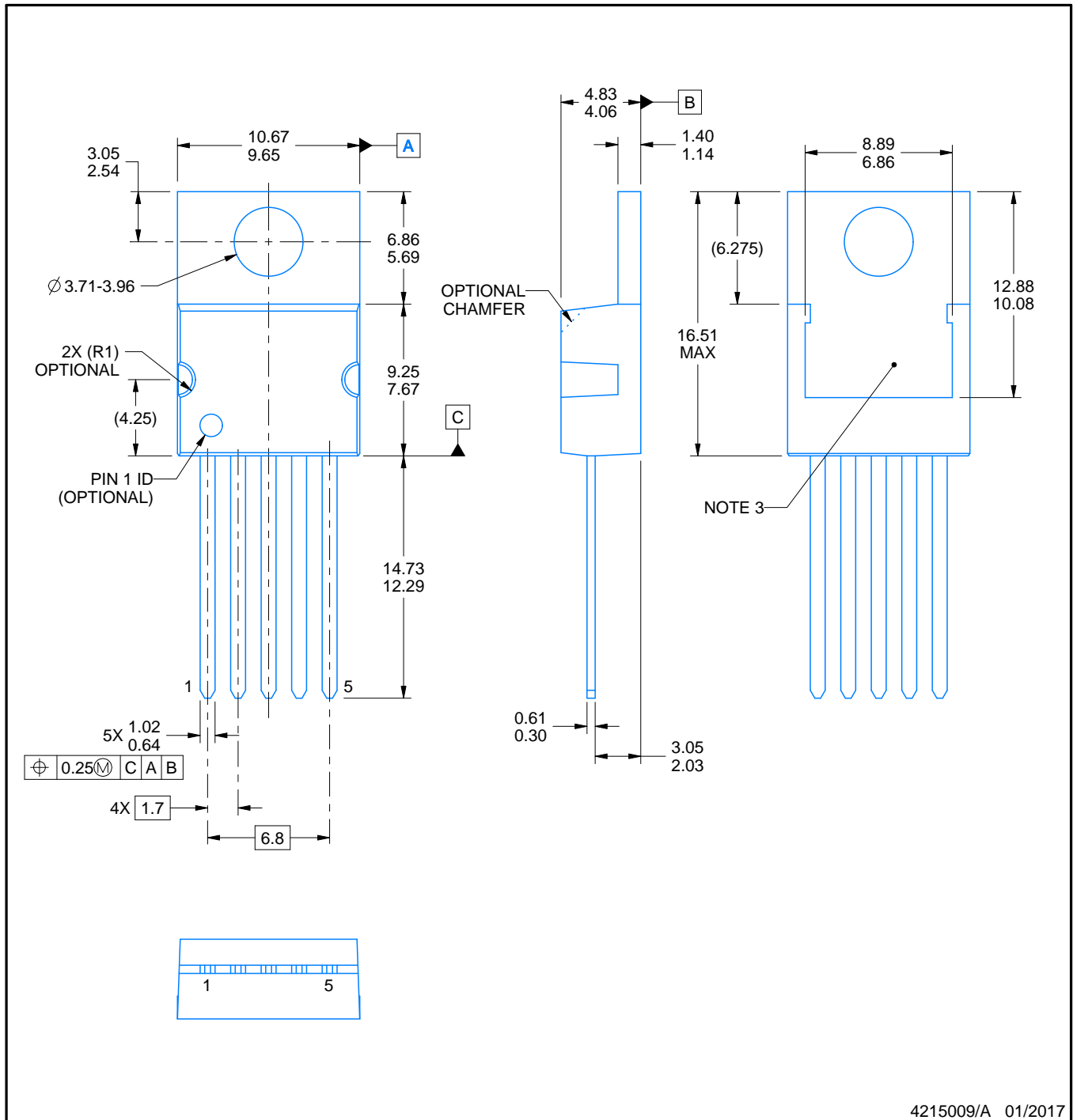
# KC0005A



# PACKAGE OUTLINE

TO-220 - 16.51 mm max height

TO-220



NOTES:

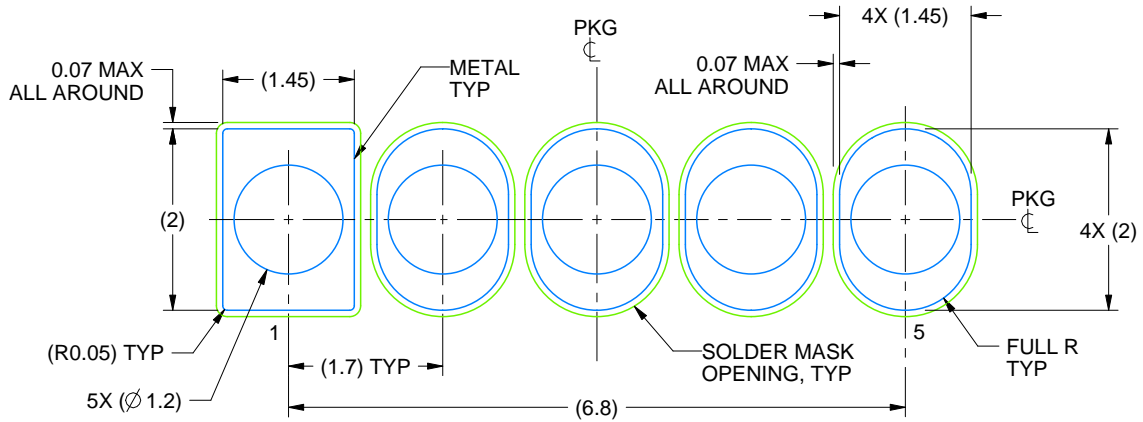
1. All controlling linear dimensions are in inches. Dimensions in brackets are in millimeters. Any dimension in brackets or parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Shape may vary per different assembly sites.

# EXAMPLE BOARD LAYOUT

KC0005A

TO-220 - 16.51 mm max height

TO-220



LAND PATTERN  
NON-SOLDER MASK DEFINED  
SCALE:12X

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